


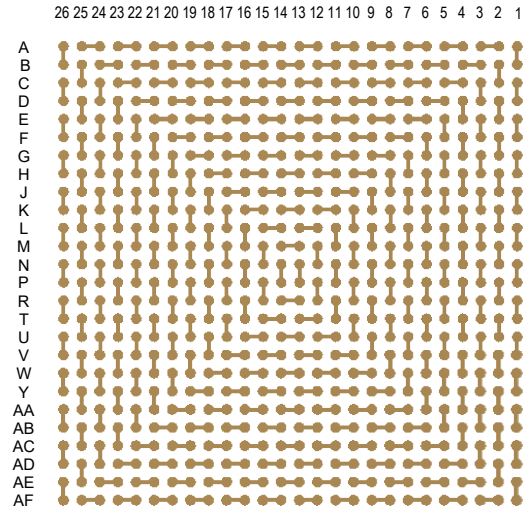
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.30mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.25mm [10 MIL].
- 5) PAD Cu DIAMETER: 0.355mm [14 MIL].
- 6) SUBSTRATE MATERIAL: BT (ALTERNATIVE FR4).
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

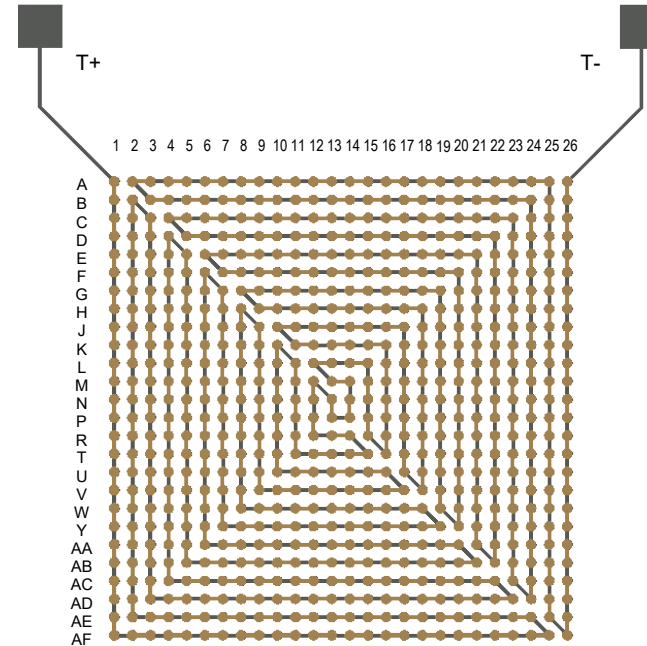
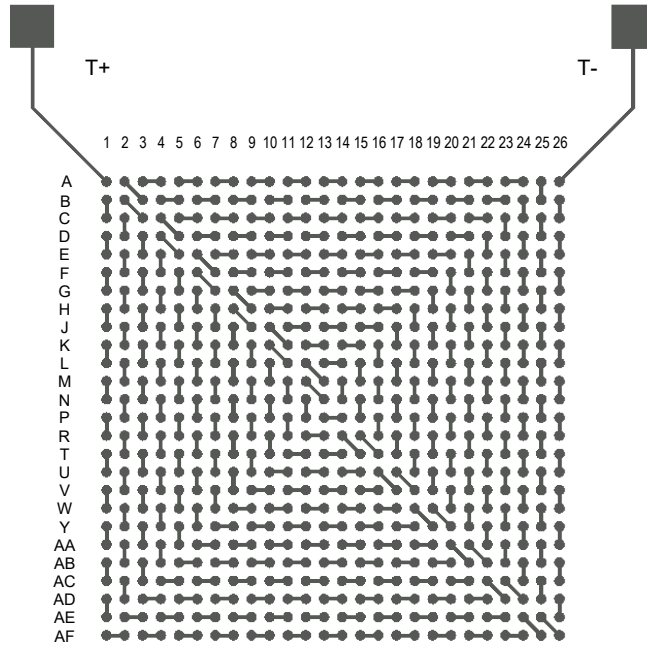
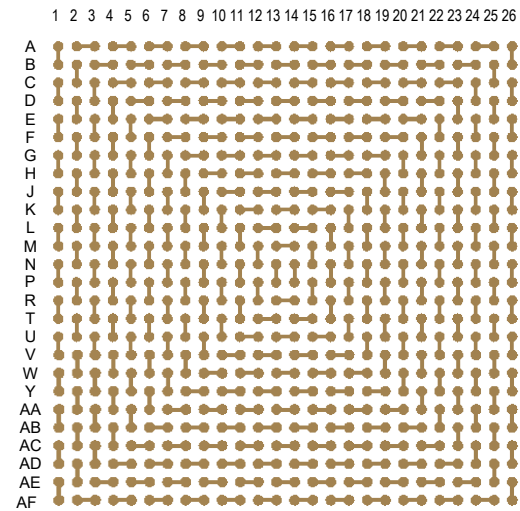
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
BGA676T.5C-DC269D	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	YES
BGA676T.5-DC269D	Sn63/Pb37	Sn63	NO	YES

APPROVALS		DATE				
DRAWN	T. Au	10/5/2021				
ENG	M. Hart	10/5/2021	TITLE		BGA676T.5-DC269D DAISY CHAIN DUMMY	
MFG			SCALE	SIZE	DRAWING NO.	REV
QA			3.5:1	A	552691	B
CUST			DO NOT SCALE DRAWING			SHEET 1 OF 3
REVISED						

BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD

AFTER MOUNTING

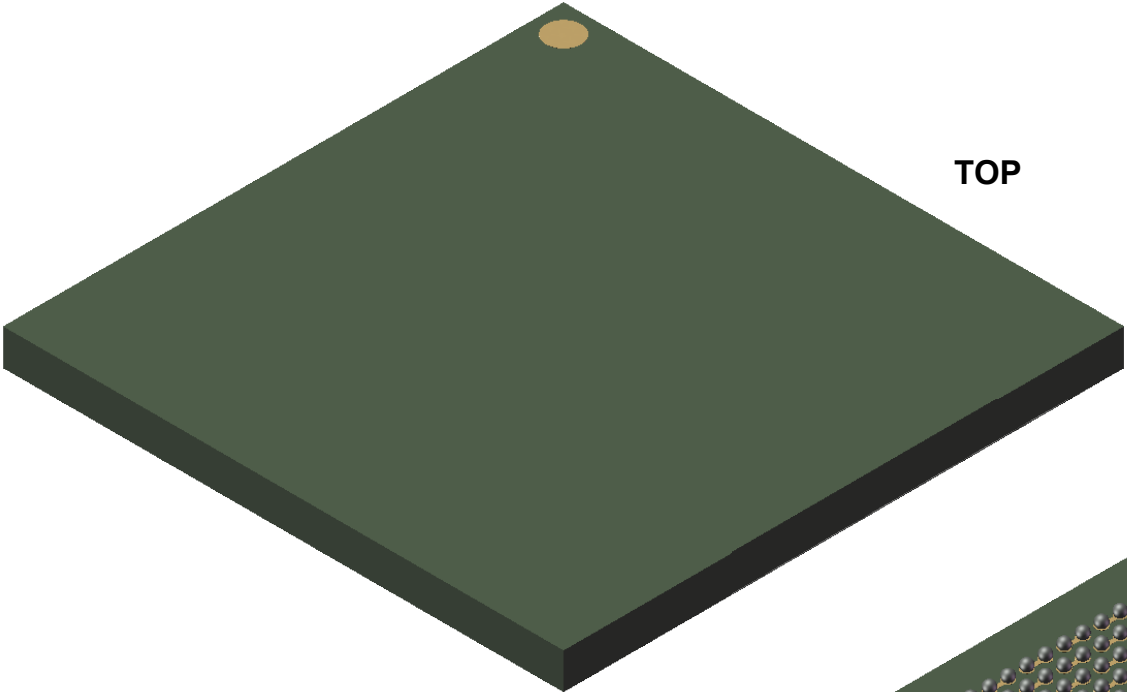
Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.355mm [14 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.127mm [5 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.25mm [10 MIL].

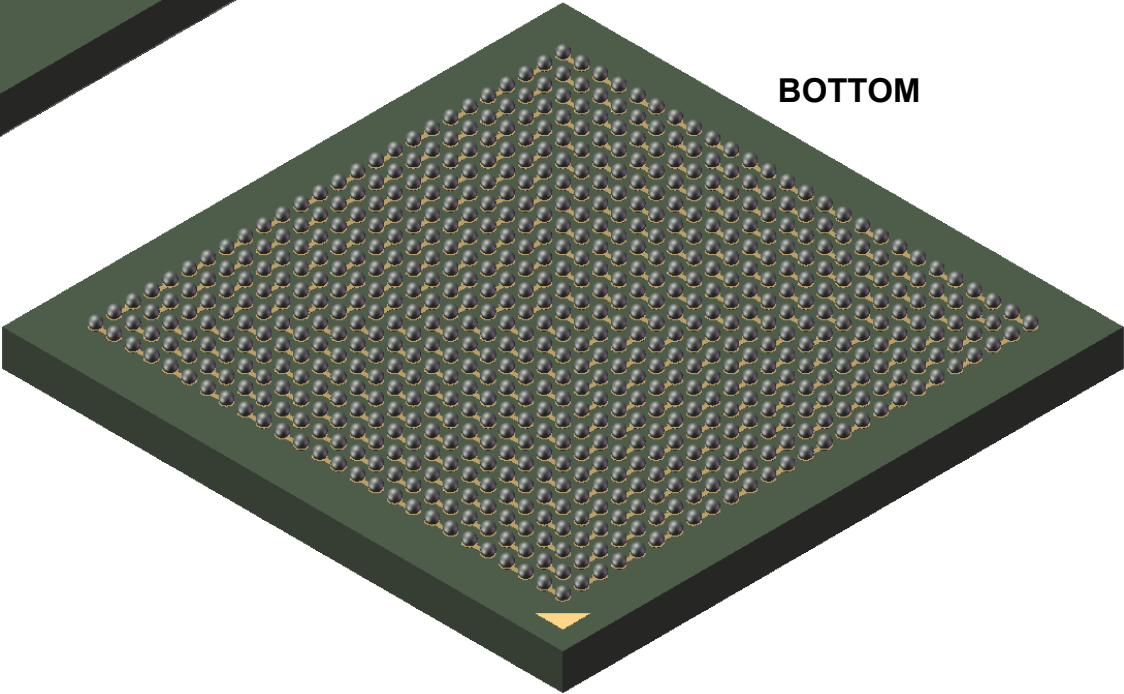


TITLE			
BGA676T.5-DC269D DAISY CHAIN DUMMY			
SCALE	SIZE	DRAWING NO.	REV
	A	552691	B
DO NOT SCALE DRAWING			SHEET 2 OF 3

MODEL



TOP



BOTTOM

TopLine®

TITLE BGA676T.5-DC269D
DAISY CHAIN DUMMY

SCALE	SIZE	DRAWING NO.	REV
	A	552691	B

DO NOT SCALE DRAWING

SHEET 3 OF 3